



Material Content Data Sheet



Sales Product Name	TDA5251			Issued		28. August 2013		
MA#	MA000218825							
Package	PG-TSSOP-38-1			Weight*		117.48 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.461	4.65	4.65	46481	46481
leadframe	non noble metal	nickel	7440-02-0	19.584	16.67		166702	
	non noble metal	iron	7439-89-6	27.045	23.02	39.69	230208	396910
wire	noble metal	gold	7440-57-5	0.900	0.77	0.77	7662	7662
encapsulation	organic material	carbon black	1333-86-4	0.178	0.15		1513	
	plastics	epoxy resin	-	7.526	6.41		64062	
	inorganic material	silicondioxide	60676-86-0	51.556	43.88	50.44	438853	504428
leadfinish	non noble metal	tin	7440-31-5	2.173	1.85	1.85	18494	18494
plating	noble metal	silver	7440-22-4	1.464	1.25	1.25	12464	12464
glue	plastics	acrylic resin	-	0.319	0.27		2712	
	noble metal	silver	7440-22-4	1.275	1.08	1.35	10849	13561
*deviation	< 10%	Sum in total:			100,00			1000000

Important Remarks:

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